

LTM8025-Pb-BGA 70LD 15mm X 9mm X 4.92mm-SOLDER DA (TABLE OF MATERIAL DECLARATION)

Contains > 1000ppm of Lead in the terminations

No.	Part Name	Material Name	Component Weight (gram)	Materials Analysis (element)	CAS Number	Material Mass (gram)	Materials Analysis (weight %)
1	Substrate	Circuit Board	0.1342	Barium Compounds	7727-43-7	0.0023	1.73
				Bismaleimide/Triazine Resin/Filter Substances(Silica Crytaline)	105391-33-1, 1156-51-0/9003-36-5/21645-51-2, non-disclosure	0.0364	27.13
				Copper Metal	7440-50-8	0.0580	43.21
				Copper Compounds	147-14-8	0.0000	0.02
				Ecotoxic substances	7440-38-2, 7440-28-0	0.0000	0.00
				Gold metal or alloy	7440-57-5	0.0006	0.48
				Nickel	7440-02-0	0.0030	2.23
				Zinc	7440-66-6	0.0000	0.03
				Continuos Filament Fiber Glass	65997-17-3	0.0286	21.32
				Acrylic Resin	non-disclosure	0.0044	3.29
				Epoxy Resin	non-disclosure	0.0000	0.02
				Chromium(III) Oxide	1308-38-9	0.0000	0.00
				Silica amorphous	7631-86-9	0.0001	0.04
				Talc;not containing fibers like asbestos	14807-96-9	0.0003	0.20
				Aromatic Carbonyl compounds	non-disclosure	0.0003	0.19
				Cyanoguanidine	461-58-5	0.0000	0.01
				Calcium caobonate	471-34-1	0.0000	0.00
				Amine compounds	non-disclosure	0.0000	0.03
				Leveling agent and others	non-disclosure	0.0001	0.08
				2	Solder Paste	Alloy	0.0155
Sb	7440-36-0	0.0008	5.00				
3	Passive/Active Components		0.8404	Iron Powder (Fe)	7439-89-6	0.5002	59.52
				Copper (Cu)	7440-50-8	0.2947	35.07
				Nickel (Ni)	7440-02-0	0.0071	0.84
				Tin (Sn)	7440-31-5	0.0369	4.39
				Ceramic (Ba compounds)	12047-27-7	0.0015	0.18
4	Active Ics	Silicon	0.0031	Silicon	7440-21-3	0.0031	100.00
5	Solder Ball	63Sn/37Pb	0.1338	Sn	7440-31-5	0.08429	63.00
				Pb	7439-92-1	0.04951	37.00
6	Wire	Gold	0.0004	Au	7440-57-5	0.0004	99.99
7	Encapsulation	Epoxy Resin	0.7975	Fused Silica	60676-86-0	0.6157	77.20
				Epoxy Resin	non-disclosure	0.0710	8.90
				Phenol Resin	non-disclosure	0.0710	8.90
				Crytalline Silica	14808-60-7	0.0239	3.00
				Carbon Black	1333-86-4	0.0040	0.50
				Metal Hydroxide	non-disclosure	0.0120	1.50
Total Package Weight			1.9250				

Note: Composition derived from MSDS and material C of C from Vendors. Component Weight based on assembly of generic parts